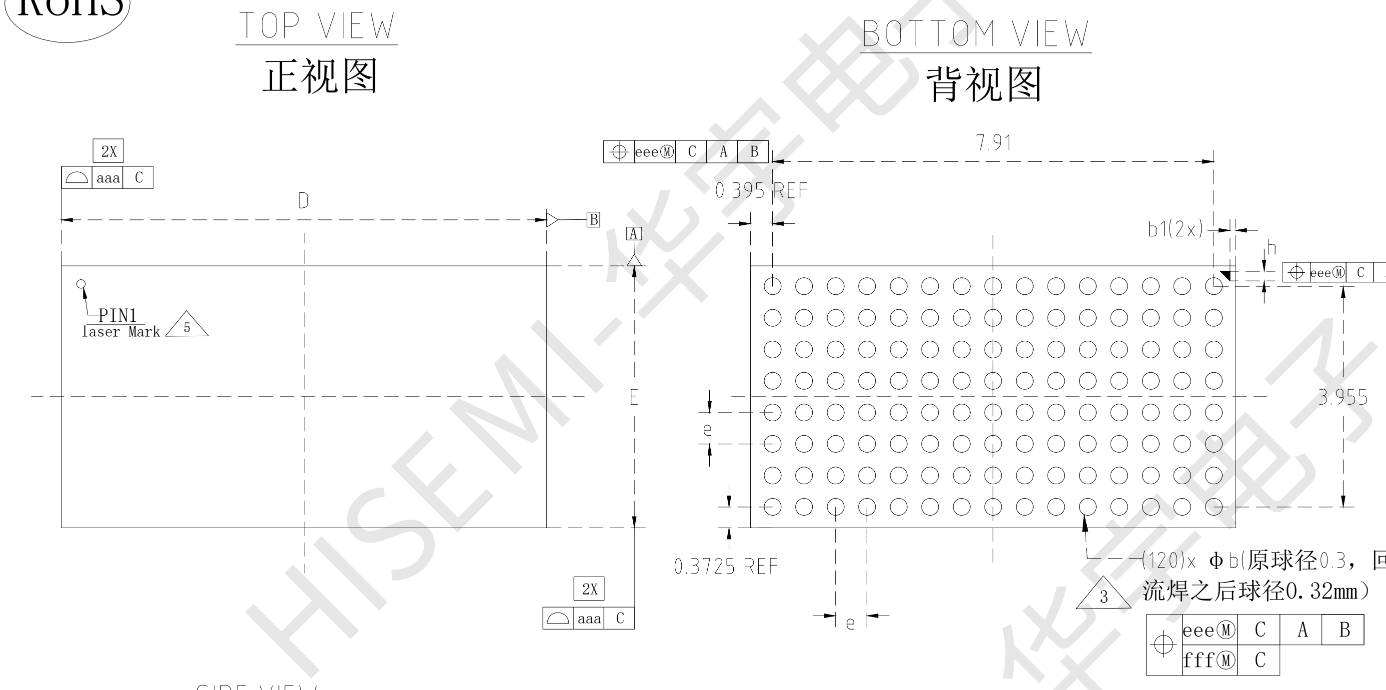
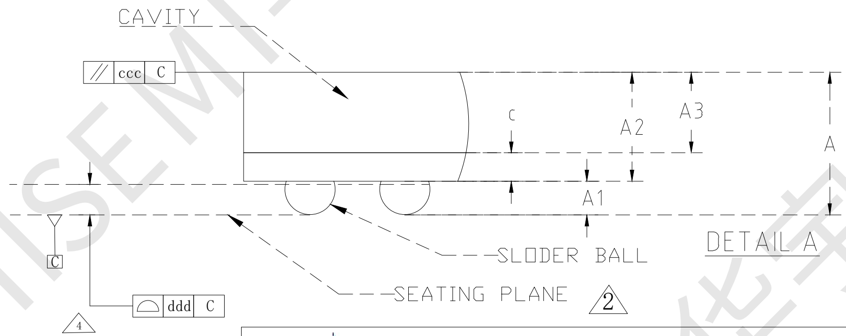
RoHS





机械尺寸/mm						
字符 SYMBOL	Dimension in mm			Dimension inch		
	最小值 MIN	典型值 NOMINAL	最大值 MAX	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	0.750	0.850	0.950	0.030	0.034	0038
A1	0.170	0.220	0.270	0.007	0.009	0.011
A2	0.570	0.620	0.670	0.023	0.025	0.027
A3	0.400	0.450	0.500	0.016	0.018	0.020
c	0.140	0.170	0.200	0.006	0.007	0.008
D	8.650	8.700	8.750	0341	0.343	0.345
E	4.650	4.700	4.750	0.183	0.185	0.187
b	0.225	0.300	0.375	0.009	0.012	0.015
e	0.565 BSC			0.023 BSC		
b1	0.050	0.100	0.150	0.002	0.004	0.006
h	0.125	0.175	0.225	0.005	0.007	0.009
aaa	0.100			0.004		
ccc	0.100			0.004		
ddd	0.100			0.004		
eee	0.100			0.004		
fff	0.100			0.004		

履历		
序号	内容	日期
1	新发行	2025.11.13
2	更新A值标注	2025.11.14
3	更新字体比例，植球标注b更新。	2025.11.18

TECHNOLOGY SPECIFICATION[技术要求]

1.BALL PAD OPENING:0.270mm;[球形防焊开口:0.270mm;]

2.PRIMARY DATUM C AND SEATING PLANE ARE THE SOLDER BALLS:
[主要基准C和底面是锡球;]

3.SDIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER,
PARALLELTO PRIMARY DATUM C;[尺寸b是测量最大锡球直径，平行于主要基准C;]

4.SPECIAL CHARACTERISTICS C CLASS:bbb, ddd:[特殊特性C类:ccc, ddd;]

5.THE PATTERN OF PIN 1 FIDUCIAL IS FOR REFERENCE ONLY;
[PIN 1标识仅供参考;]

6.BAN TO USE THE LEVEL 1 ENVIRONMENT-RELATED SUBSTANCES:
[禁止使用一级环境管理物质;]

池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

HY-POD-BGA106

PACKAGE OUTLINE DIMENSIONS
WBBGA120B(8.7X4.7X0.85-P0.565)

页数 page	单位 unit	比例 scale	视图 view
1	mm	1:1	⌖ ⏢

制图: Draw	NINGLIN 2025.11.18
制图核查: Drawing review	
审核: Checker	
核准: Approved	